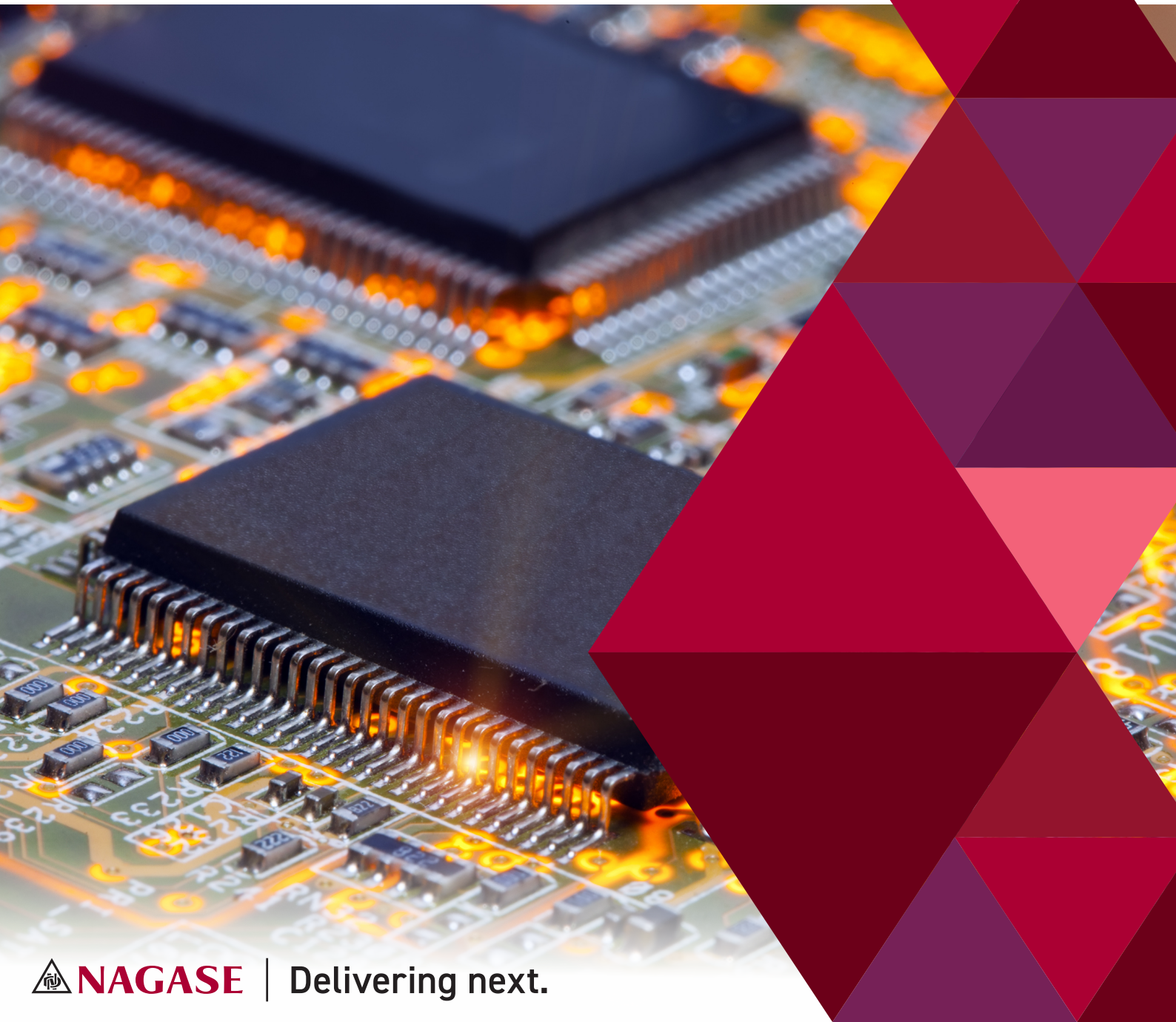


 **Materials for Power Devices and Electronic Components**

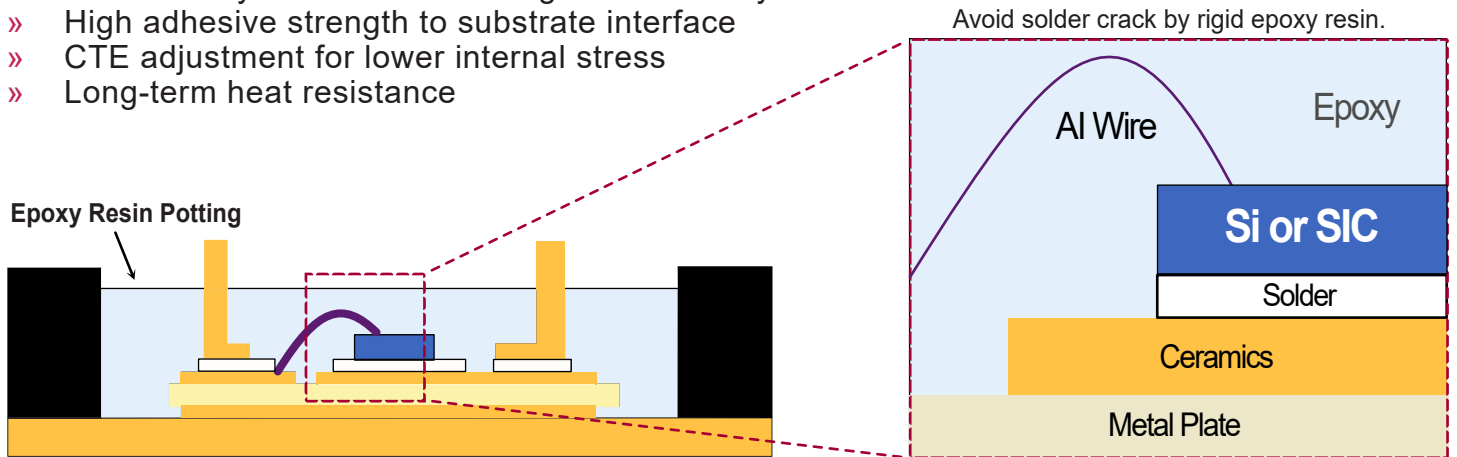
# Epoxy Potting



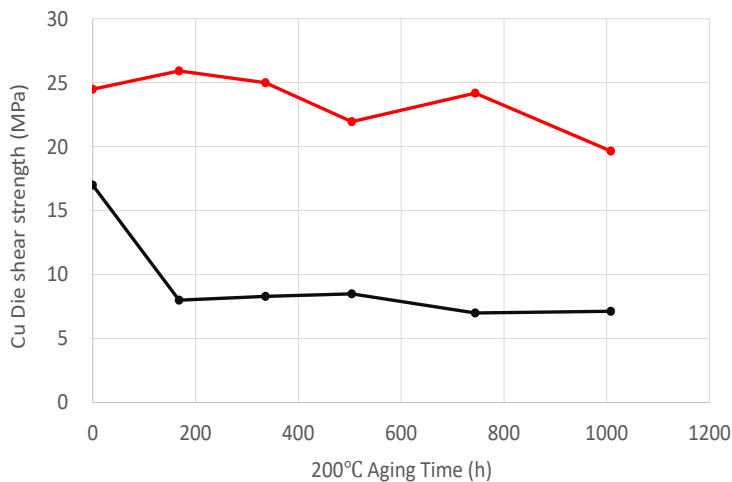
# Direct Potting Material for Power Module

## Features

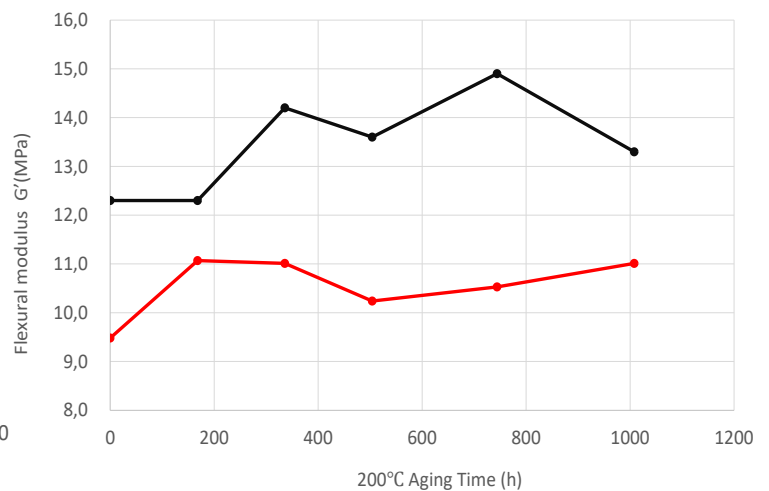
- » Flammability Level: UL V-0 halogen & antimony free
- » High adhesive strength to substrate interface
- » CTE adjustment for lower internal stress
- » Long-term heat resistance



Resin Hardener	Condition	Unit	T-700 / R-6005 T-700 / H-6005	T-700 / R-6110 T-700 / H-6110	T-700 / R6112 T-700 / H6112
Feature			High Tg Good workability	Low modulus Flammability V0 halogen free	Low CTE Flammability V0 halogen free
Curing Condition	-	-	90 °C / 3 h + 180 °C / 2 h	130 °C / 2 h + 200 °C / 2 h	130 °C / 2 h + 200 °C / 2 h
Mixture Viscosity	80 °C	Pa*s	14	28	74
Tg	DSC	°C	217	210	210
CTE	TMA	x10 <sup>-6</sup> / K	14	12	10
Flexural Modulus	DMA	GPa	13	13	15
Flammability	-	-	HB	V0	V0



— Development — Current material (acid anhydride)



— Development — Current material (acid anhydride)

